AXCELA™ PVD systems employ a scalable multi-chamber design, allowing field or factory configuration for the most flexible and cost-effective solution to a given technology application. Key innovations ensure the highest levels of processing consistency, production yield and operational reliability.

The platform consistently delivers industry-leading film uniformity, step coverage and remarkably consistent contact resistance. The system’s design, modularity and performance provide high throughput, reliable process control and high tool availability, readily sustained with simple maintenance procedures. These capabilities make the AXCELA™ platform well-suited for both high-volume production as well as low-volume R&D applications.

Performance by Design
The elegant, versatile design employs a multi-target chamber configuration, allowing for three different materials to be processed within the same chamber. Cooled by a table-chiller and a rotating stage design, the system maintains the lowest processing temperature in the industry to ensure excellent performance. Furthermore, the flexibility to conduct successive deposition cycles with different materials in the same chamber maximizes production efficiency.

Additionally, the patent-protected, dynamically oscillating magnetrons and delta-style targets in each chamber result in higher film uniformity and target life-time compared to conventional magnetron and target designs. An integrated ICP chamber and Degas incorporation within the Load Lock ensures that the wafer-lot is consistently pre-cleaned for the best process performance.
A World-Class Wafer Solution
With up to 6 multi-target deposition chambers, cooled substrate rotation and patented process technologies, the AXCELA™ platform is the most flexible and best-performing PVD system on the market today.

The AXCELA Platform
All AXCELA™ systems offer flexible chamber configuration options to meet a wide variety of process specifications. The modular design enables AXCELA™ systems to be easily maintained or upgraded in the field, providing attractive versatility and investment protection. Specific models are available for EMI Shielding, 3D/TSV, WLP and MEMS applications.

SPECIFICATIONS:
- Modular Footprint: 4.6m² – 9.5m²
- Height: 2.0m
- MTBF: > 250 hours
- Max. Power Consumption: 15-30 kWh
- Mechanical Throughput: 60 UPH
- MTTR: < 4 hours

APPLICATIONS:
- EMI Shielding
- 3D / TSV
- MEMS
- WLP

The TANGO Product Line
In addition to the AXCELA™ range, Tango also offers the reduced-footprint ONYX™: a single chamber system for specialized foundry and lower-volume production of 200mm or 300mm wafers and the multi-chamber TOPAZ™ panel system for glass and organic substrate applications of up to 530mm x 530mm.

TANGO Systems
Based in Silicon Valley, Tango Systems develops advanced PVD technology semiconductor PVD systems. With American innovation, American manufacturing and global support we deliver leading performance, high reliability and the results that matter to our worldwide customers.